Nordic Nanolab User Meeting 2024

NorFab, University of Oslo and SINTEF, Oslo, Norway 3 – 4 June 2024

Monday 3 June

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	10:30	Visits to MiNaLab						
	10:30 Registration and coffee							
	11:30	Lunch						
	12:00	Welcome						
	12:10							
	Themati	ic tutorials		Rooms				
		rials consist of 45 min inc		Characterisation: Store Auditorium				
	-	entations aim to educate	in techniques and tools	EBSD/TKD: Seminar room Caml Thin Film: Lille Auditorium				
	with a pi	ractical approach						
				Bonding/Etching: Small-Talk				
				Lithography: Simula				
	13:00	Characterisation Thin Film technol			Lithography			
		Optical techniques:	Introduction and comparison of thin film		Lithography Basics - Sample			
		Practical Raman			preparation and process variables (Basic)			
		Measurements, unwanted artefacts	deposition techniques (Basic)	intermetallic bonding for thermally challenging	Sarah Mckibbin, Lund			
		and how to avoid	Martijn de Roosz, NTNU	applications (Basic)	2-photon lithography -			
		them (Advanced)		Knut Aasmundtveit, USN	optimizing settings to			
		Jakob Thyr, Uppsala		,	achieve the best			
					compromise between print			
					time and quality , Milena De Albuquerque Moreira,			
	13:55	Anil Thilsted, Spectro Inlets: Microbudget Engineering: Converting Microfabrication Ideas into Cost-						
	10.00	Effective Start-Up Successes						
	14:30							
	15:00	Characterisation	Thin Film technologies	Bonding technologies	Lithography			
		Electrons and ions –	Combinatorial pulsed	Anisotropic conductive	Maskless lithography -			
		use cases like FIB-SEM	laser deposition (C-PLD)	adhesive film for high-	parameter control			
		tomography and TEM	an introduction. (Basic)	density interconnections	(Advanced) Grigory Skoblin,			
		lamellae (Advanced)	Magnus Andreassen, UiO		Chalmers			
		Tina Bergh, NTNU		Hoang Vu Nguyen, USN				
	15:45	Poster session		Visits to MiNaLab (15:45 - 2	17:30)			
	18:00							
	19:30	Conference dinner at Samfunnssalen in the center of Oslo						





Tuesday 4 June

09:00	Maaike Taklo, Sonitor Technologies: Unleashing Competitive Advantage by Embracing MEMS Technology					
09:45	Characterisation	Thin Film technologies	Etching technologies	Lithography		
	EBSD/TKD intro (Basic) Alice Bastos da Silva Fanta, DTU	Thin Film deposition by magnetron sputtering: Insights in process development and process control. (Intermediate) Stefan Mertin, VTT	Ion Beam Etching (Basic) Mats Hagberg, Chalmers	High-Resolution Hexagonal Patterns Fabricated by Dipole Cross Exposure in Deep UV- Lithography and their Applications (Basic to more advanced) Matthias Keil /Meena Dhankar		
10:30	Coffee					
11:00	Characterisation Demo: Analyzing EBSD/TKD data with hyperspy, kikuchipy (Basic/advanced) Håkon Ånes, NTNU	Thin Film technologies Thin film super- conductors grown on silicon for single photon detectors by different deposition methods: Molecular Beam Epitaxy versus Sputtering. (Intermediate) Adrian Iovan, KTH		Lithography E-Beam&UV Mix-and-Match (<i>Basic to advanced</i>) Thomas Pedersen /Elena López- Aymerich, DTU Nanolab		
11:55	·					
12:30	Lunch					
13:15	Characterisation X-ray diffraction (XRD) (Basic) Evgeniy Shkondin, DTU	Thin Film technologies Pulsed Laser Deposition: From High Temperature Superconductors to Atomically Engineered Interfaces. (Advanced) Alexei Kalaboukhov, Chalmers		Lithography Automated metrology for improved E-beam lithography (Advanced) Niclas Lindvall,Chalmers Focused Ion Beam Lithography, Andreas Liapis, Aalto		
14:00	Coffee					
14:15 14:50						
15:15	Bus to Gardermoen					



